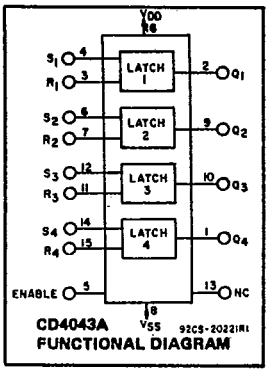
CD4043A, CD4044A Types

CMOS Quad 3-State R/S Latches

Quad NOR R/S Latch – CD4043A
Quad NAND R/S Latch – CD4044A

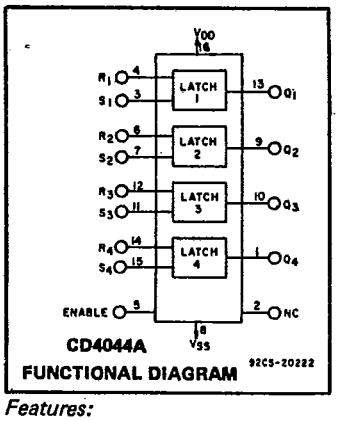
The RCA-CD4043A types are quad cross-coupled 3-state CMOS NOR latches and the CD4044A types are quad cross-coupled 3-state CMOS NAND latches. Each latch has a separate Q output and individual SET and RESET inputs. The Q outputs are controlled by a common ENABLE input. A logic "1" or high on the ENABLE input connects the latch states to the Q outputs. A logic "0" or low on the ENABLE input disconnects the latch states from the Q outputs, resulting in an open circuit condition on the Q outputs. The open circuit feature allows common busing of the outputs. The logic operation of the latches is summarized in the truth table shown in Fig. 1.

These types are supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic package (E suffix), 16-lead ceramic flat packages (K suffix), and in chip form (H suffix).



Applications:

- Holding register in multi-register system
- Four bits of independent storage with output ENABLE
- Strobed register
- General digital logic



Features:

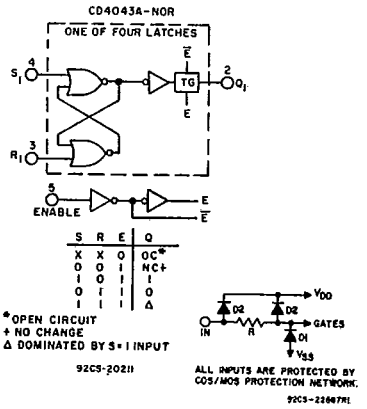
- 3-Level outputs with common output ENABLE
- Separate SET and RESET inputs for each latch
- NOR and NAND configurations
- Quiescent current specified to 15 V
- Maximum input leakage of 1 μA at 15 V (full package-temperature range)
- 1-V noise margin (full package-temperature range)

MAXIMUM RATINGS, *Absolute-Maximum Values:*

STORAGE-TEMPERATURE RANGE (T_{stg}) . . . . . –65 to +150°C
OPERATING-TEMPERATURE RANGE (T_A):
  PACKAGE TYPES D, F, K, H . . . . . –55 to +125°C
  PACKAGE TYPE E . . . . . –40 to +85°C
DC SUPPLY-VOLTAGE RANGE, (V_{DD})
  (Voltages referenced to V_{SS} Terminal): . . . . . –0.5 to +15 V
POWER DISSIPATION PER PACKAGE (P_D):
  FOR T_A = –40 to +60°C (PACKAGE TYPE E) . . . . . 500 mW
  FOR T_A = +60 to +85°C (PACKAGE TYPE E) . . . . . Derate Linearly at 12 mW/°C to 200 mW
  FOR T_A = –55 to +100°C (PACKAGE TYPES D, F, K) . . . . . 500 mW
  FOR T_A = +100 to +125°C (PACKAGE TYPES D, F, K) . . . Derate Linearly at 12 mW/°C to 200 mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
  FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (ALL PACKAGE TYPES) . . . . . 100 mW
INPUT VOLTAGE RANGE, ALL INPUTS . . . . . –0.5 to V_{DD} +0.5 V
LEAD TEMPERATURE (DURING SOLDERING):
  At distance 1/16 ± 1/32 inch (1.59 ±0.79 mm) from case for 10 s max . . . . . +265°C

RECOMMENDED OPERATING CONDITIONS at T_A = 25°C, Except as Noted.
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	V_{DD} (V)	LIMITS				UNITS
		D, F, K, H Packages		*E Package*		
		Min.	Max.	Min.	Max.	
Supply-Voltage Range (For T_A = Full Package Temperature Range	–	3	12	3	12	V
Set or Reset Pulse Width, t_W	5 10	200 100	– –	225 110	– –	ns



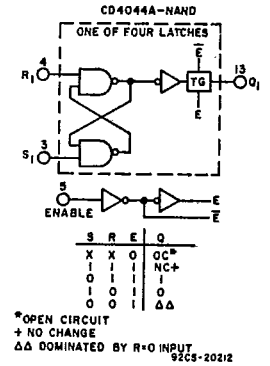


Fig. 1 – Logic diagrams and truth tables.

STATIC ELECTRICAL CHARACTERISTICS

Characteristic	Conditions			Limits at Indicated Temperatures (°C)								Units
				D, F, K, H Packages				E Package				
	V_O (V)	V_{IN} (V)	V_{DD} (V)	−55	+25 Typ.	+25 Limit	+125	−40	+25 Typ.	+25 Limit	+85	
Quiescent Device Current, I_L Max.	–	–	5	1	0.005	1	60	10	0.01	10	140	μA
	–	–	10	2	0.005	2	120	20	0.02	20	280	
	–	–	15	25	0.25	25	1000	250	2.5	250	2500	
Output Voltage: Low-Level, V_{OL}	–	0,5	5	0 Typ.; 0.05 Max.								V
	–	0,10	10	0 Typ.; 0.05 Max.								
High Level, V_{OH}	–	0,5	5	4.95 Min.; 5 Typ.								
	–	0,10	10	9.95 Min.; 10 Typ.								
Noise Immunity: Inputs Low, V_{NL}	4.2	–	5	1.5 Min.; 2.25 Typ.								V
	9	–	10	3 Min.; 4.5 Typ.								
Inputs High, V_{NH}	0.8	–	5	1.5 Min.; 2.25 Typ.;								
	1	–	10	3 Min.; 4.5 Typ.								
Noise Margin: Inputs Low, V_{NML}	4.5	–	5	1 Min.								V
	9	–	10	1 Min.								
Inputs High, V_{NMH}	0.5	–	5	1 Min.								
	1	–	10	1 Min.								
Output Drive Current: n-Channel (Sink), I_DN Min.	0.5	–	5	0.25	0.5	0.2	0.19	0.12	0.5	0.1	0.09	mA
	0.5	–	10	0.61	1	0.5	0.35	0.3	1	0.25	0.22	
p-Channel (Source), I_DP Min.	4.5	–	5	-0.22	-0.5	-0.175	-0.12	-0.11	-0.5	-0.09	-0.08	
	9.5	–	10	-0.5	-1	-0.4	-0.28	-0.24	-1	-0.2	-0.18	
Input Leakage Current, I_{IL}, I_{IH}	Any Input		15	$\pm 10^{-5}$ Typ.; ±1 Max.								μA

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C; Input t_r, t_f = 20 ns, C_L = 15 pF, R_L = 200 kΩ

CHARACTERISTIC	V_{DD} (V)	LIMITS				UNITS
		D, F, K, H Packages		E Package		
		Typ.	Max.	Typ.	Max.	
Propagation Delay Time: t_{PHL}, t_{PLH} SET or RESET to Q	5	175	350	175	400	ns
	10	75	175	75	200	
3-State Propagation Delay Time: ENABLE to Q t_{PHZ}, t_{PZH}	5	100	200	100	200	ns
	10	50	100	50	100	
t_{PLZ}, t_{PZL}	5	80	160	80	160	ns
	10	40	80	40	80	
Transition Time: t_{THL}, t_{PLH}	5	100	200	100	250	ns
	10	50	100	50	125	
Minimum SET or RESET Pulse Width, t_W	5	80	200	80	225	ns
	10	40	100	40	110	
Average Input Capacitance, C_I (Any Input)	–	5	–	5	–	pF

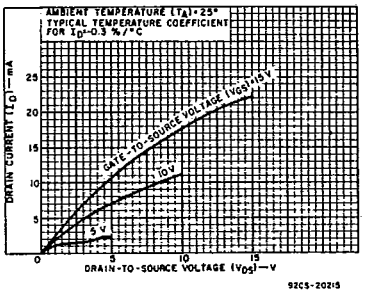


Fig. 2 — Typical output n-channel drain characteristics.

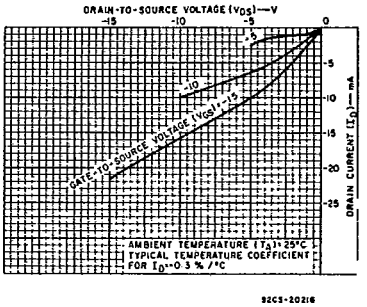


Fig. 3 — Typical output p-channel drain characteristics.

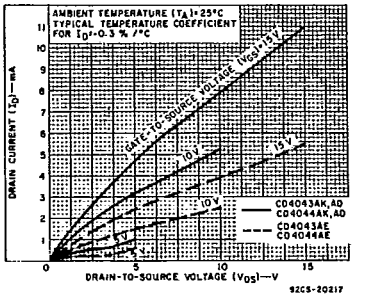


Fig. 4 — Minimum n-channel drain characteristics.

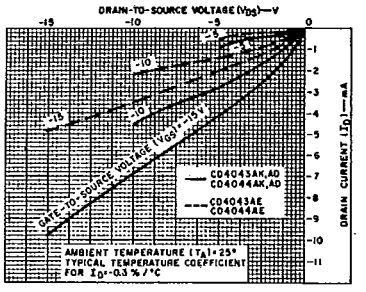


Fig. 5 — Minimum p-channel drain characteristics.

CD4043A, CD4044A Types

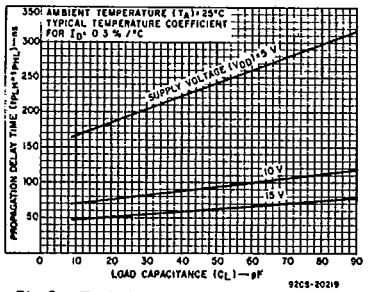


Fig. 6 – Typical propagation delay time vs. C_L.

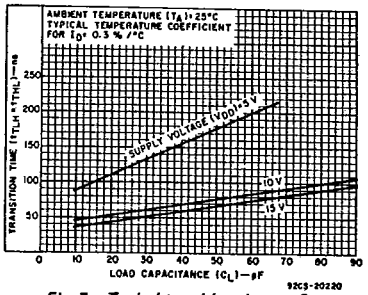


Fig. 7 – Typical transition time vs. C_L.

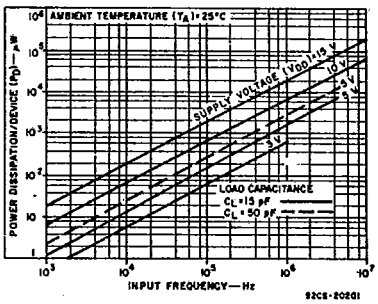


Fig. 8 – Typical dissipation characteristics.

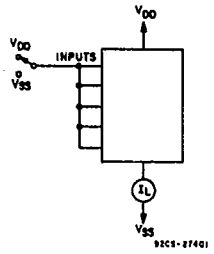


Fig. 9 – Quiescent device current test circuit.

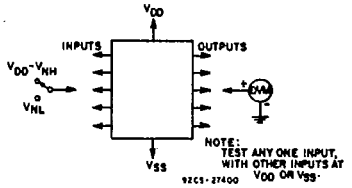


Fig. 10 – Noise immunity test circuit.

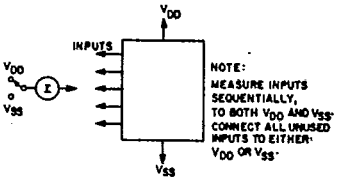


Fig. 11 – Input leakage current test circuit.

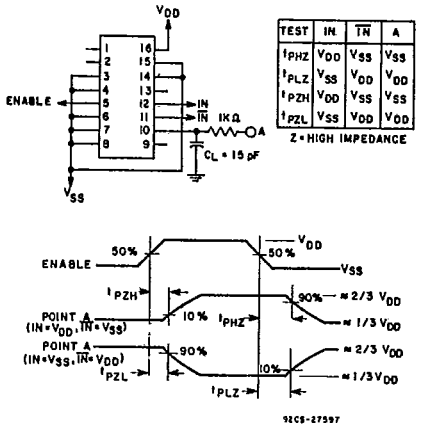


Fig. 12 – ENABLE propagation delay time test circuit and waveforms.

APPLICATIONS

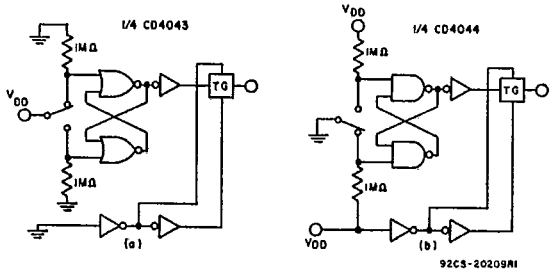


Fig. 13 – Switch bounce eliminator.

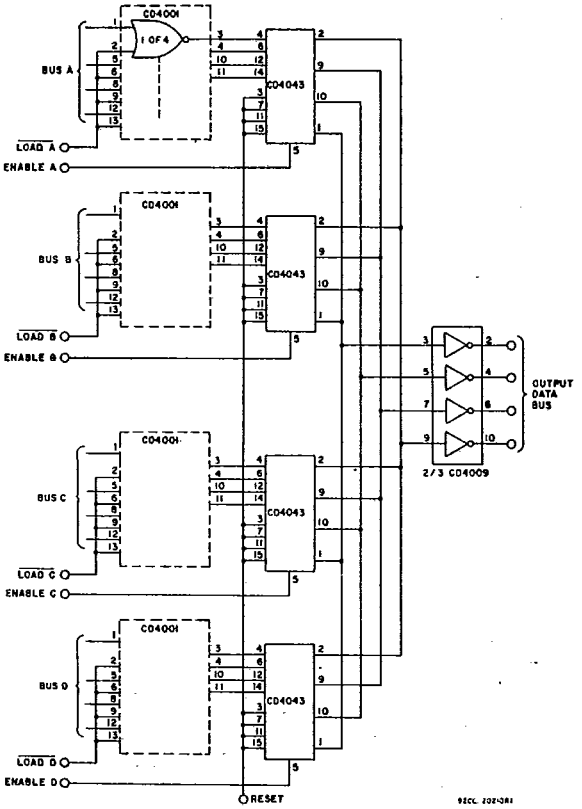
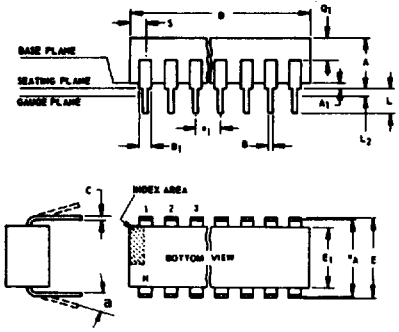


Fig. 14 – Multiple bus storage.

Dimensional Outlines

Dual-In-Line Welded-Seal Ceramic Packages



NOTES:
Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.
1. When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
3. e_A applies in zone L_2 when unit installed.
4. α applies to spread leads prior to installation.
5. N is the maximum quantity of lead positions.
6. N_1 is the quantity of allowable missing leads.

(D) SUFFIX (JEDEC MO-001-AD)
14-Lead Dual-In-Line Welded-Seal Ceramic Package

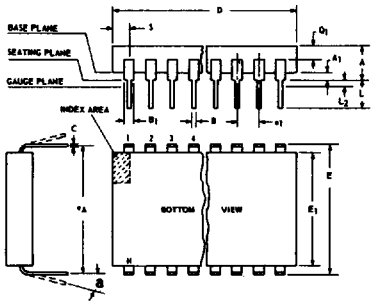
SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.160		3.05	4.06
A_1	0.020	0.065		0.51	1.65
B	0.014	0.020		0.356	0.508
B_1	0.050	0.065		1.27	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.770		18.93	19.55
E	0.300	0.325		7.62	8.25
E_1	0.240	0.260		6.10	6.60
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L_2	0.000	0.030		0.000	0.76
α	0°	15°	4	0°	15°
N	14		5	14	
N_1	0		6	0	
Q_1	0.050	0.085		1.27	2.15
S	0.065	0.090		1.66	2.28

92SS-4411R2

(D) SUFFIX (JEDEC MO-001-AE)
16-Lead Dual-In-Line Welded-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.160		3.05	4.06
A_1	0.020	0.065		0.51	1.65
B	0.014	0.020		0.356	0.508
B_1	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.785		18.93	19.93
E	0.300	0.325		7.62	8.25
E_1	0.240	0.260		6.10	6.60
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L_2	0.000	0.030		0.000	0.76
α	0°	15°	4	0°	15°
N	16		5	16	
N_1	0		6	0	
Q_1	0.050	0.085		1.27	2.15
S	0.015	0.060		0.39	1.52

92SS-4286R5



NOTES:
Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.
1. When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
3. e_A applies in zone L_2 when unit installed.
4. α applies to spread leads prior to installation.
5. N is the maximum quantity of lead positions.
6. N_1 is the quantity of allowable missing leads.

(D) SUFFIX (JEDEC MO-015-AG)
24-Lead Dual-In-Line Welded-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.090	0.200		2.29	5.08
A_1	0.020	0.070		0.51	1.78
B	0.015	0.020		0.381	0.508
B_1	0.045	0.055		1.143	1.397
C	0.008	0.012	1	0.204	0.304
D	1.15	1.22		29.21	30.98
E	0.600	0.625		15.24	15.87
E_1	0.480	0.520		12.20	13.20
e_1	0.100 TP		2	2.54 TP	
e_A	0.600 TP		2,3	15.24 TP	
L	0.100	0.180		2.54	4.57
L_2	0.000	0.030		0.00	0.76
α	0°	15°	4	0°	15°
N	24		5	24	
N_1	0		6	0	
Q_1	0.020	0.080		0.51	2.03
S	0.020	0.060		0.51	1.52

92CS-19948R4

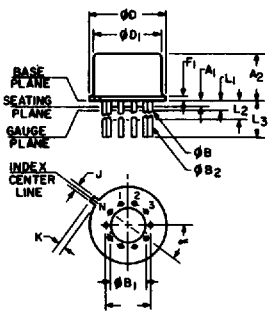
(D) SUFFIX (JEDEC MO-015-AH)
28-Lead Dual-In-Line Welded-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.090	0.200		2.29	5
A_1	0	0.070	2	0	1.77
B	0.015	0.020		0.381	0.508
B_1	0.015	0.055		0.39	1.39
C	0.008	0.012	1	0.204	0.304
D	1.380	1.420		35.06	36.06
E	0.600	0.625		15.24	15.87
E_1	0.485	0.515		12.32	13.08
e_1	0.100 TP		2	2.54 TP	
e_A	0.600 TP		2,3	15.24 TP	
L	0.100	0.200		2.8	5
L_2	0	0.030		0	0.76
α	0°	15°	4	0°	15°
N	28		5	28	
N_1	0		6	0	
Q_1	0.020	0.070		0.51	1.77
S	0.040	0.070		1.02	1.77

92CM-20250R2

TO-5 Style Package

(T) SUFFIX (JEDEC MO-006-AG)
12-Lead Metal Package



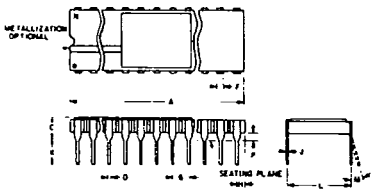
92CS-19774

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
a	0.230		2	5.84 TP	
A_1	0	0		0	0
A_2	0.165	0.185		4.19	4.70
ϕB	0.016	0.019	3	0.407	0.482
ϕB_1	0	0		0	0
ϕB_2	0.016	0.021	3	0.407	0.533
ϕD	0.335	0.370		8.51	9.39
ϕD_1	0.305	0.335		7.75	8.50
F_1	0.020	0.040		0.51	1.01
j	0.028	0.034		0.712	0.863
k	0.029	0.045	4	0.74	1.14
L_1	0.000	0.050	3	0.00	1.27
L_2	0.250	0.500	3	6.4	12.7
L_3	0.500	0.562	3	12.7	14.27
α	30° TP			30° TP	
N	12		6	12	
N_1	1		5	1	

NOTES:
1. Refer to Rules for Dimensioning Axial Lead Product Outlines.
2. Leads at gauge plane within 0.007" (0.178 mm) radius of True Position (TP) at maximum material condition.
3. ϕB applies between L_1 and L_2. ϕB_2 applies between L_2 and 0.500" (12.70 mm) from seating plane. Diameter is uncontrolled in L_1 and beyond 0.500" (12.70 mm).
4. Measure from Max. ϕD.
5. N_1 is the quantity of allowable missing leads.
6. N is the maximum quantity of lead positions.

Dimensional Outlines (Cont'd)

DUAL-IN-LINE SIDE-BRAZED CERAMIC PACKAGES



NOTES:
1. Leads within 0.005" (0.13 mm)-radius of True Position at maximum material condition.
2. Dimension "L" to center of leads when formed parallel.
3. When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).

(D) SUFFIX
18-Lead Dual-In-Line
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.890	0.915		22.606	23.241
C	–	0.200		–	5.080
D	0.015	0.021		0.381	0.533
F	0.054 REF.		1	1.371 REF.	
G	0.100 BSC		1	2.54 BSC	
H	0.035	0.065		0.889	1.651
J	0.008	0.012	3	0.203	0.304
K	0.125	0.150		3.175	3.810
L	0.290	0.310	2	7.366	7.874
M	0°	15°		0°	15°
P	0.025	0.045		0.635	1.143
N	18			18	

92CS-27231R1

(D) SUFFIX
22-Lead Dual-In-Line
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.065	1.100		27.05	27.94
C	0.085	0.145		2.16	3.68
D	0.017	0.023		0.43	0.58
F	0.040 REF.		1	1.02 REF.	
G	0.100 BSC		1	2.54 BSC	
H	0.030	0.070		0.76	1.78
J	0.008	0.012	3	0.20	0.30
K	0.125	0.175		3.18	4.45
L	0.380	0.420	2	9.65	10.67
M	–	7°		–	7°
P	0.025	0.050		0.64	1.27
N	22			22	

92CS-25186R2

(D) SUFFIX
24-Lead Dual-In-Line
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.180	1.220		29.98	30.98
C	0.085	0.145		2.16	3.68
D	0.015	0.023		0.39	0.58
F	0.040 REF.			1.02 REF.	
G	0.100 BSC		1	2.54 BSC	
H	0.030	0.070		0.77	1.77
J	0.008	0.012	3	0.21	0.30
K	0.125	0.175		3.18	4.44
L	0.580	0.620	2	14.74	15.74
M	–	7°		–	7°
P	0.025	0.050		0.64	1.27
N	24			24	

92CS-30986R1

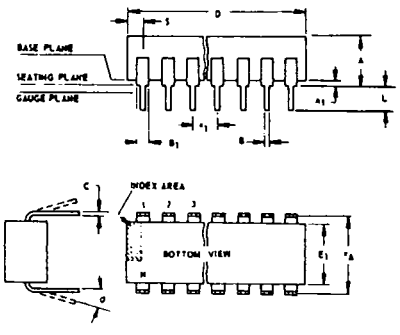
(D) SUFFIX
40-Lead Dual-In-Line
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.980	2.020		50.30	51.30
C	0.095	0.155		2.43	3.93
D	0.017	0.023		0.43	0.56
F	0.050 REF.			1.27 REF.	
G	0.100 BSC		1	2.54 BSC	
H	0.030	0.070		0.76	1.78
J	0.008	0.012	3	0.20	0.30
K	0.125	0.175		3.18	4.45
L	0.580	0.620	2	14.74	15.74
M	–	7°		–	7°
P	0.025	0.050		0.64	1.27
N	40			40	

92CM-27029R2

Dual-In-Line Plastic and Frit-Seal Ceramic Packages

(E) SUFFIX (JEDEC MO-001-AN)
8-Lead Dual-In-Line Plastic
(Mini-DIP) Package



SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A_1	0.020	0.050		0.508	1.27
B	0.014	0.020		0.356	0.508
B_1	0.035	0.065		0.889	1.65
C	0.008	0.012	1	0.203	0.304
D	0.370	0.400		9.40	10.16
E	0.300	0.325		7.62	8.25
E_1	0.240	0.260		6.10	6.60
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L_2	0.000	0.030		0.000	0.762
α	0	15	4	0	15
N	8		5	8	
N_1	0		6	0	
Q_1	0.040	0.075		1.02	1.90
S	0.015	0.060		0.381	1.52

92CS-24026R1

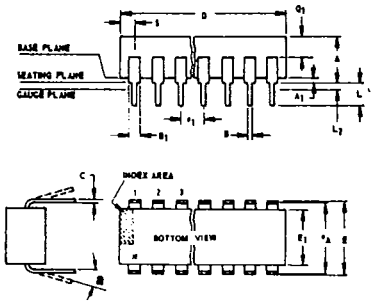
NOTES:

Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.

1. When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013".
2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at guage plane with maximum material condition and unit installed.
3. e_A applies in zone L_2 when unit installed.
4. α applies to spread leads prior to installation.
5. N is the maximum quantity of lead positions.
6. N_1 is the quantity of allowable missing leads.

Dimensional Outlines (Cont'd)

Dual-In-Line Plastic and Frit-Seal Ceramic Packages (Cont'd)



NOTES:
Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.
1. When this device is supplied solder dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
3. e_A applies in zone L_2 when unit installed.
4. α applies to spread leads prior to installation.
5. N is the maximum quantity of lead positions.
6. N_1 is the quantity of allowable missing leads.

(E) and (F) SUFFIXES (JEDEC MO-001-AB)
14-Lead Dual-In-Line Plastic or Frit-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A_1	0.020	0.060		0.51	1.27
B	0.014	0.020		0.356	0.508
B_1	0.050	0.065		1.27	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.770		18.93	19.55
E	0.300	0.325		7.62	8.25
E_1	0.240	0.260		6.10	6.60
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L_2	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	14		5	14	
N_1	0		6	0	
Q_1	0.040	0.075		1.02	1.90
S	0.065	0.090		1.66	2.28

92SS-4296R3

(E) and (F) SUFFIXES (JEDEC MO-001-AC)
16-Lead Dual-In-Line Plastic or Frit-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A_1	0.020	0.050		0.51	1.27
B	0.014	0.020		0.356	0.508
B_1	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.785		18.93	19.93
E	0.300	0.325		7.62	8.25
E_1	0.240	0.260		6.10	6.60
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L_2	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	16		5	16	
N_1	0		6	0	
Q_1	0.040	0.075		1.02	1.90
S	0.015	0.060		0.39	1.52

92CM-15967R4

(E) SUFFIX
18-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A_1	0.020	0.050		0.508	1.27
B	0.014	0.020		0.356	0.508
B_1	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D	0.845	0.885		21.47	22.47
E_1	0.240	0.260		6.10	6.60
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2,3	7.62 TP	
L	0.125	0.150		3.18	3.81
a	0°	15°	4	0°	15°
N	18		5	18	
N_1	0		6	0	
S	0.015	0.060		0.39	1.52

92CS-30630

(E) SUFFIX
22-Lead Dual-In-Line Plastic Package

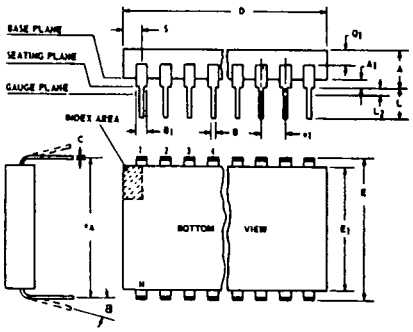
SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A_1	0.020	0.050		0.508	1.27
B	0.015	0.020		0.381	0.508
B_1	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D		1.120			28.44
E	0.390	0.420		9.91	10.66
E_1	0.345	0.355		8.77	9.01
e_1	0.100 TP		2	2.54 TP	
e_A	0.400 TP		2, 3	10.16 TP	
L	0.125	0.150		3.18	3.81
L_2	0	0.030		0	0.762
a	2°	15°	4	2°	15°
N	22		5	22	
N_1	0		6	0	
Q_1	0.055	0.085		1.40	2.15
S	0.015	0.060		0.381	1.27

92CS-30830

(F) SUFFIX (JEDEC MO-001-AG)
16-Lead Dual-In-Line Frit-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.165	0.210		4.20	5.33
A_1	0.015	0.045		0.381	1.14
B	0.015	0.020		0.381	0.508
B_1	0.045	0.070		1.15	1.77
C	0.009	0.011	1	0.229	0.279
D	0.750	0.795		19.05	20.19
E	0.295	0.325		7.50	8.25
E_1	0.245	0.300		6.23	7.62
e_1	0.100 TP		2	2.54 TP	
e_A	0.300 TP		2, 3	7.62 TP	
L	0.120	0.160		3.05	4.06
L_2	0.000	0.030		0.000	0.76
a	2°	15°	4	2°	15°
N	16		5	16	
N_1	0		6	0	
Q_1	0.050	0.080		1.27	2.03
S	0.010	0.060		0.254	1.52

92CM-22284R1



NOTES:
Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.
1. When this device is supplied solder dipped, the maximum lead thickness (narrow portion) will not exceed 0.013".
2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at guage plane with maximum material condition and unit installed
3. e_A applies in zone L_2 when unit installed.
4. α applies to spread leads prior to installation.
5. N is the maximum quantity of lead positions.
6. N_1 is the quantity of allowable missing leads.

(E) and (F) SUFFIXES (JEDEC MO-015-AA)
24-Lead Dual-In-Line Plastic or Frit-Seal Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.250		3.10	6.30
A_1	0.020	0.070		0.51	1.77
B	0.016	0.020		0.407	0.508
B_1	0.028	0.070		0.72	1.77
C	0.008	0.012	1	0.204	0.304
D	1.20	1.29		30.48	32.76
E	0.600	0.625		15.24	15.87
E_1	0.515	0.580		13.09	14.73
e_1	0.100 TP		2	2.54 TP	
e_A	0.600 TP		2,3	15.24 TP	
L	0.100	0.200		2.54	5.00
L_2	0.000	0.030		0.00	0.76
a	0°	15°	4	0°	15°
N	24		5	24	
N_1	0		6	0	
Q_1	0.040	0.075		1.02	1.90
S	0.040	0.100		1.02	2.54

92CS26938R2

(E) SUFFIX
40-Lead Dual-In-Line Plastic Package

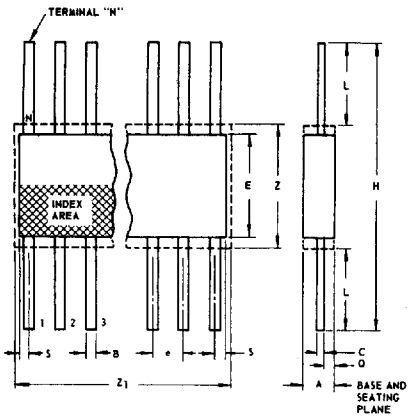
SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.250		3.10	6.30
A_1	0.020	0.070		0.51	1.77
B	0.016	0.020		0.407	0.508
B_1	0.028	0.070		0.72	1.77
C	0.008	0.012	1	0.204	0.304
D	2.000	2.090		50.80	53.09
E_1	0.515	0.580		13.09	14.73
e_1	0.100 TP		2	2.54 TP	
e_A	0.600 TP		2,3	15.24 TP	
L	0.100	0.200		2.54	5.00
L_2	0.000	0.030		0.00	0.76
a	0°	15°	4	0°	15°
N	40		5	40	
N_1	0		6	0	
Q_1	0.065	0.095		1.66	2.41
S	0.040	0.100		1.02	2.54

92CS-30959

Dimensional Outlines (Cont'd)

Ceramic Flat Packs

(K) SUFFIX (JEDEC MO-004-AF)
14-Lead



SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.008	0.100		0.21	2.54
B	0.015	0.019	1	0.381	0.482
C	0.003	0.006	1	0.077	0.152
e	0.050 TP		2	1.27 TP	
E	0.200	0.300		5.1	7.6
H	0.600	1.000		15.3	25.4
L	0.150	0.350		3.9	8.8
N	14		3	14	
Q	0.005	0.050		0.13	1.27
S	0.000	0.050		0.00	1.27
Z	0.300		4	7.62	
Z_1	0.400		4	10.16	

92SS-4300R3

NOTES:
1. Refer to JEDEC Publication No. 95 for Rules for Dimensioning Peripheral Lead Outlines.
2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at maximum material condition.
3. N is the maximum quantity of lead positions.
4. Z and Z_1 determine a zone within which all body and lead irregularities lie.

(K) SUFFIX (JEDEC MO-004-AG)
16-Lead

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.008	0.100		0.21	2.54
B	0.015	0.019	1	0.381	0.482
C	0.003	0.006	1	0.077	0.152
e	0.050 TP		2	1.27 TP	
E	0.200	0.300		5.1	7.6
H	0.600	1.000		15.3	25.4
L	0.150	0.350		3.9	8.8
N	16		3	16	
Q	0.005	0.050		0.13	1.27
S	0.000	0.025		0.00	0.63
Z	0.300		4	7.62	
Z_1	0.400		4	10.16	

92CS-17271R3

(K) SUFFIX
24-Lead

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.075	0.120		1.91	3.04
B	0.018	0.022	1	0.458	0.558
C	0.004	0.007	1	0.102	0.177
e	0.050 TP		2	1.27 TP	
E	0.600	0.700		15.24	17.78
H	1.150	1.350		29.21	34.29
L	0.225	0.325		5.72	8.25
N	24		3	24	
Q	0.035	0.070		0.89	1.77
S	0.060	0.110	1	1.53	2.79
Z	0.700		4	17.78	
Z_1	0.750		4	19.05	

92CS-19949R2

(K) SUFFIX
28-Lead

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.075	0.120		1.91	3.04
B	0.018	0.022	1	0.458	0.558
C	0.004	0.007	1	0.102	0.177
e	0.050 TP		2	1.27 TP	
E	0.600	0.700		15.24	17.78
H	1.150	1.350		29.21	34.29
L	0.225	0.325		5.72	8.25
N	28		3	28	
Q	0.035	0.070		0.89	1.77
S	0	0.060	1	0	1.53
Z	0.700		4	17.78	
Z_1	0.750		4	19.05	

92CS-20972